

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

73944-5003

Status:

Active

Overview:

HDM® Backplane Connector System

Description:

HDM® Board-to-Board Backplane Header, Vertical, SMC, Solder Tail, Guide Pin Option, 144 Circuits

Documents:

3D Model

Drawing (PDF)

Product Specification PS-73670-9999 (PDF)

RoHS Certificate of Compliance (PDF)

Agency Certification

CSA

UL

LR19980

E29179

General

Product Family

Series

Application

Component Type

Overview

Product Name

Style

UPC

Backplane Connectors

73944

Backplane

PCB Header

HDM® Backplane Connector System

HDM®

N/A

800756628875

Physical

Circuits (Loaded)

Circuits (maximum)

Color - Resin

Durability (mating cycles max)

First Mate / Last Break

Flammability

Guide to Mating Part

Keying to Mating Part

Material - Metal

Material - Plating Mating

Material - Plating Termination

Material - Resin

Number of Columns

Number of Pairs

Number of Rows

Orientation

PC Tail Length

PCB Locator

PCB Retention

PCB Thickness - Recommended

Packaging Type

Pitch - Mating Interface

Pitch - Termination Interface

Plating min - Mating

Plating min - Termination

Polarized to PCB

Stackable

Surface Mount Compatible (SMC)

Temperature Range - Operating

Termination Interface: Style

144

144

Black, Natural

250

No

94V-0

Yes

Yes

Phosphor Bronze, Stainless Steel

Gold

Tin

High Temperature Thermoplastic

24

Open Pin Field

6

Vertical

3.00mm

No

None

2.50mm

Tube

2.00mm

2.00mm

0.762µm

2.540µm

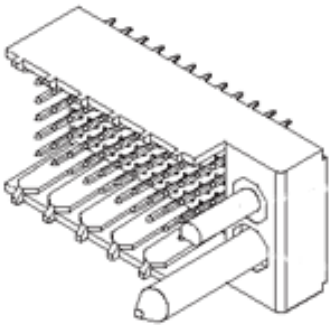
No

Yes

Yes

-55°C to +105°C

Through Hole



Series

image - Reference only

EU RoHS

ELV and RoHS

Compliant

REACH SVHC

Not Reviewed

Low-Halogen Status

Not Reviewed

China RoHS



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series
73944Series

Mates With
73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | [FAQ](#)
Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Extraction Tool	0621001000
Backplane Insertion	0621001400
Signal Contact Tool	
Backplane Insertion	0622005703
Head for 144 Circuits	

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Product Specification	PS-73670-9999
Sales Drawing	SD-73944-001

HDM and High Density Metric are trademarks of Amphenol Corporation

This document was generated on 12/09/2014

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Mouser Electronics

Authorized Distributor

Click to View Pricing, Inventory, Delivery & Lifecycle Information:

[Molex:](#)

[73944-5003](#)